



## Material Content Data Sheet



<b>Sales Product Name</b>		BFP 760 H6327		<b>Issued</b>		26. January 2016			
<b>MA#</b>		MA001038234							
<b>Package</b>		PG-SOT343-4-2		<b>Weight*</b>		6.93 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.003	0.04		389		
	non noble metal	tin	7440-31-5	0.001	0.01		100		
	inorganic material	silicon	7440-21-3	0.023	0.34	0.39	3387	3876	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100		
	non noble metal	titanium	7440-32-6	0.003	0.05		498		
	non noble metal	chromium	7440-47-3	0.010	0.15		1493		
	non noble metal	copper	7440-50-8	3.433	49.54	49.75	495507	497598	
wire	noble metal	gold	7440-57-5	0.010	0.15	0.15	1467	1467	
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4371		
	plastics	epoxy resin	-	0.651	9.40		93974		
	inorganic material	silicondioxide	60676-86-0	2.347	33.87	43.71	338745	437090	
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28755	28755	
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31214	31214	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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